

GENERAL INFORMATION

Your proposal should include:

- The title of your paper
- Information about its author(s) (title, full name, position, company, address, department, telephone and fax numbers, e-mail address, together with brief biographical details) clearly indicating the lead author (speaker)
- The conference topic addressed by your proposal
- A summary of no less than 2 pages with facts, figures, drawings, anything needed to get a good understanding of final paper
- It should be sent to us in digital format PDF
- Abstracts non respecting those recommendations will be rejected without further notice

Additional information:

Speakers will be allocated 30 minutes each (20 minutes for presentation and 10 minutes for questions). All necessary instructions for the preparation of papers will be sent to the selected authors.

The lead author (only 1 per paper) will benefit a free access to the conference as a speaker.

Conference language: English (no simultaneous translation)

Deadlines:

- Proposals for papers must reach us by September 15, 2010
- Presented papers will be selected by programme committees and experts of the field for academic papers.
- The authors will be notified accordingly by mid November 15, 2010
- Before February 28, 2011, the authors selected must submit a text on their presentation for inclusion in conference proceedings.

Some of the papers might be selected to be published in the "Ingénieur de l'Automobile", EPE journal, Mov'eo publications and others related events we are connected to.

EXHIBITION, SPONSORSHIP & ADVERTISEMENT

The congress will be accompanied by an exhibition where companies will be able to present information to the participants, highlight their new products and create new privileged contacts within this unique gathering of targeted decision-makers.

The exhibition will be a focal point, attracting professionals, research institutes and engineers from the electronic and the automotive industries. This offer is limited, and it is highly recommended to book your space as early as possible.

You have also the possibility to maximize your visibility by becoming a sponsor. With a corporate sponsorship, you gain unmatched recognition as an industry leader and generate an abundance of goodwill. Consider this sponsorship opportunity.

Do not miss the opportunity to advertise in the congress documents: a portal to leading decision-makers in the automotive industry.

Your contact Emilie BONNET – emilie.bonnet@sia.fr – Tel: +33 (0)1 41 44 93 75

TOPICS TO BE ADDRESSED

APE 2011 special focus: Power Electronics for Electric Vehicles

A – Power Systems & auxiliaries (present requirements & forecast needs):

1. Automotive applications: power systems & components,
2. Power electronic vehicle architecture : e-powertrain alternative solutions, choice of network voltages, add-in smart converters, local storage ...
3. 'Cutting edge' technologies & roadmaps,
4. Advanced power applications functions & systems: blowers, e-steering, e-braking, new energy generators, thermal comfort, lightning ...
5. Alternative power network: multi-voltage, stability, protection, distribution, quality, cost effectiveness.

B - Power Components (actives & passives):

1. Power converters and drives,
2. Semiconductor smart modules, devices, and dedicated drivers,
3. Packaging and integration of power converters: including protection devices...
4. Passive components: new materials & 3D integration solutions,
5. New materials for power packaging, cooling, heat transfer, internal routing,
6. Harnesses and connectors, protection/distribution devices,
7. High temperature electronics: components, connections, packaging, testing ...

C – Mechatronics (from integration technologies to affordable diagnosis):

1. E-actuators & drives: mechatronics integration & synergetic impact,
2. Multi-function materials/devices for more integrated solutions,
3. Power dissipation management, heat transfer, innovative cooling,
4. On board diagnosis opportunity : smart architecture, virtual sensors, computed failure prognosis,
5. Cost effective solutions : integration vs standardization,
6. Dedicated design tools.

D – Battery management: (system & components):

1. Battery management: control, signal, and power level,
2. Battery chargers, slow/fast, stand alone/others,
3. Dedicated sensors, smart cooling and innovative routing,
4. Connectors, protection & distribution devices,
5. Connection to the grid.

E – Robust design & Cost effective manufacturing (design & benches):

1. Robustness validation process for design and manufacturing,
2. Components reliability methodology, failure analysis, and test benches,
3. Virtual life time assessment modeling: physics of failure, end-of-life tests, health management and life-time prognosis,
4. Intelligent testing: acceleration factors, smart benches, link with modeling,
5. Dependability standards; fail silent/fault tolerant designs vs cost effectiveness,
6. Multi - domain/physics issues: modeling & simulation,
7. Tools interoperability.

Any other paper presented on a topic not quoted above but having scientific, technical or strategic interest will be taken into consideration.

4th INTERNATIONAL CONFERENCE AND EXHIBITION

AUTOMOTIVE POWER - ELECTRONICS

APRIL 6 & 7, 2011
PARIS, FRANCE

Moving forward together
Progressons ensemble



OVERVIEW & OBJECTIVES

SIA is launching the 4th edition of APE “Automotive Power Electronics” Conference and Exhibition.

Automotive world is facing a amazing revolution coming trough power electronics, to bring a new generation of affordable green cars.

APE conference is involving both communities of automotive power R&D and industry power R&D (as well as leading labs involved !) to get the best on this strategically increasing domain. It focuses on “in-car” systems & components, dealing with all aspects of related power electronics and electrification of vehicles targeting very low CO₂ emissions.

A wide range is concerned:

- Applications for passenger vehicles, buses, and light duty vehicles,
- Innovative technical / technological solutions and new dedicated development tools solutions,
- Power levels: from 100 W up to 100 KW,
- Applications for Internal Combustion Engine Vehicles (ICEV), hybrid vehicles (HV & PHEV), and electrical vehicles (EV),
- Ambitious mitigation of automotive stresses: Electrical, Thermal, Chemical, Mechanical, EMC and most effective combinations of them, bringing always more reliable products.

APE will offer you in one location: high level scientific and technical conferences, a unique platform for top-level engineers/researchers exchanges, and an exhibition covering a wide range of products and services in the field of automotive power electronics.

In summary, APE provides you – from labs early modeling to series processes tuning - an exclusive moment of conviviality, networking and knowledge sharing among automobile engineers and specialists in the field of world wild power electronics.



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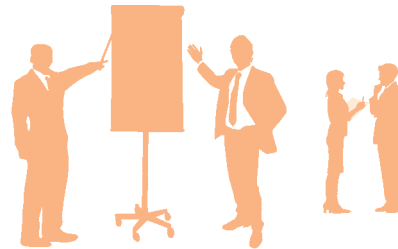
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